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April 2007

## FDG8850NZ

# Dual N-Channel PowerTrench<sup>®</sup> MOSFET 30V,0.75A,0.4 $\Omega$

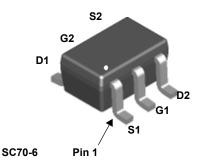
#### **Features**

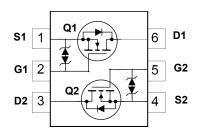
- Max  $r_{DS(on)} = 0.4\Omega$  at  $V_{GS} = 4.5V$ ,  $I_D = 0.75A$
- Max  $r_{DS(on)} = 0.5\Omega$  at  $V_{GS} = 2.7V$ ,  $I_D = 0.67A$
- Very low level gate drive requirements allowing operation in 3V circuits(V<sub>GS(th)</sub> <1.5V)
- Very small package outline SC70-6
- RoHS Compliant



#### **General Description**

This dual N-Channel logic level enhancement mode field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance. This device has been designed especially for low voltage applications as a replacement for bipolar digital transistors and small signal MOSFETs. Since bias resistors are not required, this dual digital FET can replace several different digital transistors, with different bias resistor values.





## MOSFET Maximum Ratings T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
$V_{DS}$	Drain to Source Voltage		30	V
$V_{GS}$	Gate to Source Voltage		±12	V
	Drain Current -Continuous		0.75	
ID	-Pulsed		2.2	A
Б	Power Dissipation for Single Operation	(Note 1a)	0.36	10/
$P_{D}$		(Note 1b)	0.30	W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range		-55 to +150	°C

#### **Thermal Characteristics**

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient Single operation	(Note 1a)	350	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient Single operation	(Note 1b)	415	C/VV

#### **Package Marking and Ordering Information**

Device Marking	Device	Reel Size	Tape Width	Quantity
.50	FDG8850NZ	7"	8mm	3000 units

## Electrical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units			
Off Chara	Off Characteristics								
$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	30			V			
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250μA, referenced to 25°C		25		mV/°C			
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 24V, V_{GS} = 0V$			1	μА			
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 12V, V_{DS} = 0V$			±10	μΑ			

#### On Characteristics

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	0.65	1.0	1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I <sub>D</sub> = 250μA, referenced to 25°C		-3.0		mV/°C
r <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 4.5V, I_D = 0.75A$ $V_{GS} = 2.7V, I_D = 0.67A$ $V_{GS} = 4.5V, I_D = 0.75A, T_J = 125^{\circ}C$		0.25 0.29 0.36	0.4 0.5 0.6	Ω
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 5V, I_{D} = 0.75A$		3		S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance		90	120	pF
Coss	Output Capacitance	$V_{DS}$ = 10V, $V_{GS}$ = 0V, f= 1MHZ	20	30	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		15	25	pF

#### **Switching Characteristics** (note 2)

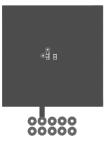
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t <sub>d(on)</sub>	Turn-On Delay Time		4	10	ns
t <sub>r</sub>	Rise Time	$V_{DD} = 5V, I_D = 0.5A,$	1	10	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 4.5V, R_{GEN} = 6\Omega$	9	18	ns
t <sub>f</sub>	Fall Time		1	10	ns
$Q_g$	Total Gate Charge		1.03	1.44	nC
$Q_{gs}$	Gate to Source Charge	$V_{GS}$ =4.5V, $V_{DD}$ = 5V, $I_{D}$ = 0.75A	0.29		nC
$Q_{ad}$	Gate to Drain "Miller" Charge		0.17		nC

### **Drain-Source Diode Characteristics and Maximum Ratings**

Is	Maximum Continuous Drain-Source Diode Forward Current				0.3	Α
$V_{SD}$	Source to Drain Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 0.3A$	(Note 2)	0.76	1.2	V

#### Notes:

<sup>1.</sup> R<sub>0,IA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>θ,IC</sub> is guaranteed by design while R<sub>θ,IA</sub> is determined by the user's board design.



a.  $350^{\circ}\text{C/W}$  when mounted on a 1 in<sup>2</sup> pad of 2 oz copper .



b. 415°C/W when mounted on a minimum pad of 2 oz copper.

Scale 1:1 on letter size paper.

2. Pulse Test: Pulse Width < 300 $\mu$ s, Duty cycle < 2.0%.

## Typical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

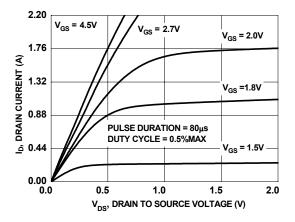
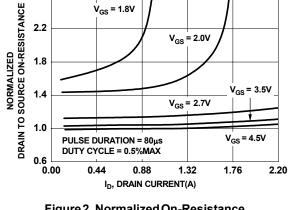


Figure 1. On-Region Characteristics



2.6

Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

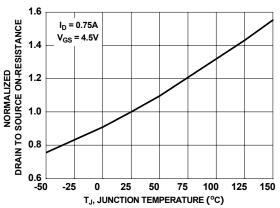


Figure 3. Normalized On - Resistance vs Junction Temperature

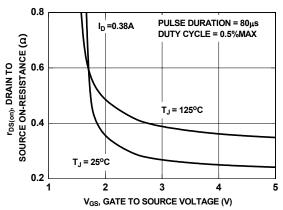


Figure 4. On-Resistance vs Gate to Source Voltage

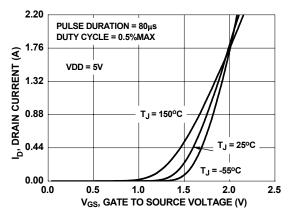


Figure 5. Transfer Characteristics

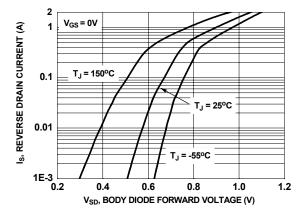


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

## **Typical Characteristics** $T_J = 25^{\circ}C$ unless otherwise noted

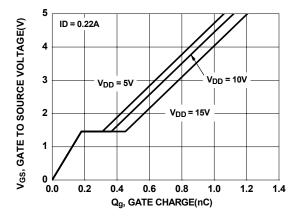


Figure 7. Gate Charge Characteristics

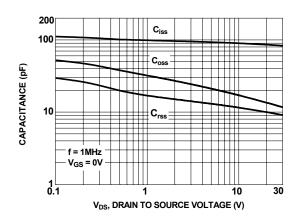
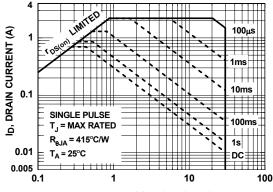


Figure 8. Capacitance vs Drain to Source Voltage



V<sub>DS</sub>, DRAIN to SOURCE VOLTAGE (V) Figure 9. Forward Bias Safe Operating Area

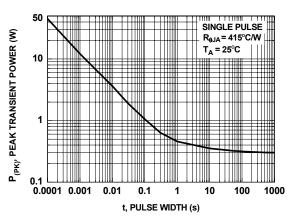


Figure 10. Single Pulse Maximum Power Dissipation

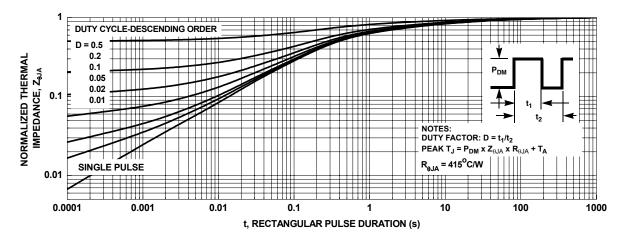


Figure 11. Transient Thermal Response Curve





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